

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	49	361/772-774,813.ccls. and (chip die ic) with lead with (above over) with (chip die ic) same (encapsulant\$3 mold\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/28 20:50
L2	350	361/772-774,813.ccls. and (chip die ic) with (lead loc) same (chip die ic) and (encapsulant\$3 mold\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/28 20:51
L3	16	361/772-774,813.ccls. and (chip die ic) and (lead loc) and (chip die ic) and (encapsulant\$3 mold\$3) and mosfet	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/28 20:52
L4	387	361/772-774,813.ccls. and (chip die ic) same (lead loc) and (chip die ic) and (encapsulant\$3 mold\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/28 20:53

	Type	Hits	Search Text
237	BRS	337	257/288,341,350,666,672,676,690,692-695,734,784,786,e23.014,e23.031,e23.033.ccls. and mosfet same (chip die ic) and wire
238	BRS	2253	257/288,341,350,666,672,676,690,692-695,734,784,786,e23.014,e23.031,e23.033.ccls. and (chip die ic) with lead with (above over) with (chip die ic)
239	BRS	154	S298 and MOSFET
240	BRS	1637	257/288,341,350,666,672,676,690,692-695,734,784,786,e23.014,e23.031,e23.033.ccls. and (chip die ic) with lead with (above over) with (chip die ic) and (encapsulant\$3 mold\$3)
241	BRS	694	257/288,341,350,666,672,676,690,692-695,734,784,786,e23.014,e23.031,e23.033.ccls. and (chip die ic) with lead with (above over) with (chip die ic) same (encapsulant\$3 mold\$3)